DRV8835 Dual Low-Voltage H-Bridge IC

1 Features

- Dual-H-Bridge Motor Driver
  - Capable of Driving Two DC Motors or One Stepper Motor
  - Low-MOSFET ON-Resistance: HS + LS 305 mΩ
- 1.5-A Maximum Drive Current Per H-Bridge
- Configure Bridges Parallel for 3-A Drive Current
- Separate Motor and Logic-Supply Pins:
  - 0-V to 11-V Motor-Operating Supply-Voltage
  - 2-V to 7-V Logic Supply-Voltage
- Separate Logic and Motor Power Supply Pins
- Flexible PWM or PHASE/ENABLE Interface
- Low-Power Sleep Mode With 95-nA Maximum Supply Current
- Tiny 2.00-mm × 3.00-mm WSON Package

2 Applications

- Battery-Powered:
  - Cameras
  - DSLR Lenses
  - Consumer Products
  - Toys
  - Robotics
  - Medical Devices

3 Description

The DRV8835 provides an integrated motor driver solution for cameras, consumer products, toys, and other low-voltage or battery-powered motion control applications. The device has two H-bridge drivers, and drives two DC motors or one stepper motor, as well as other devices like solenoids. The output driver block for each consists of N-channel power MOSFETs configured as an H-bridge to drive the motor winding. An internal charge pump generates gate drive voltages.

The DRV8835 supplies up to 1.5-A of output current per H-bridge and operates on a motor power supply voltage from 0 V to 11 V, and a device power supply voltage of 2 V to 7 V.

PHASE/ENABLE and IN/IN interfaces are compatible with industry-standard devices.

Internal shutdown functions are provided for overcurrent protection, short circuit protection, undervoltage lockout, and overtemperature.

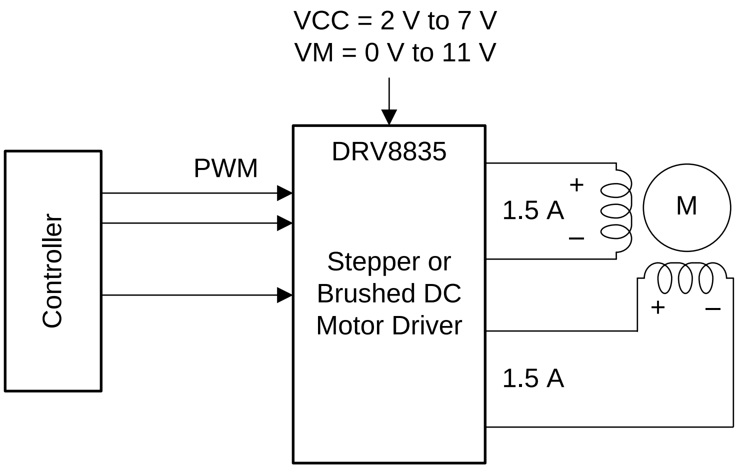
The DRV8835 is packaged in a tiny 12-pin WSON package (Eco-friendly: RoHS and no Sb/Br).

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
DRV8835	WSON (12)	2.00 mm × 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision G (May 2016) to Revision H	Page
• Changed the value of the capacitor on the VM pin from 10 µF to 0.1 µF in the *Parallel Mode Connections* figure	12
• Added one capacitor to the VM pin and updated the value of the existing capacitor on the VM pin in the *Layout Example*	15
• Deleted references to TI's PowerPAD package and updated it with *thermal pad* where applicable	16
• Added the *Receiving Notification of Documentation Updates* section	17

Changes from Revision F (April 2016) to Revision G	Page
• Changed the *Layout Guidelines* to clarify the guidelines for the VM pin	15

Changes from Revision E (December 2015) to Revision F	Page
• Deleted nFAULT from the *Simplified Schematic* in the *Description* section	1

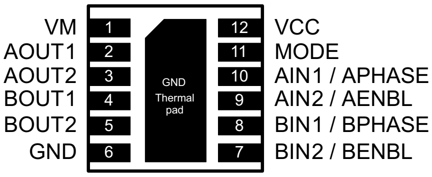
Changes from Revision D (January 2014) to Revision E	Page
• Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1

Changes from Revision C (September 2013) to Revision D Page

- Changed *Features* bullet 1
- Changed motor supply voltage range in *Description* section 1
- Changed Motor power supply voltage range in *Recommended Operating Conditions* 5
- Added t_{OCR} and t_{DEAD} parameters to *Electrical Characteristics* 6
- Added paragraph to *Power Supplies* and *Input Pins* section 14

5 Pin Configuration and Functions

DSS Package
12-Pin WSON With Exposed Thermal Pad
Top View



Pin Functions

PIN		I/O (1)	DESCRIPTION	EXTERNAL COMPONENTS OR CONNECTIONS
NAME	NO.			
POWER AND GROUND				
GND, Thermal pad	6	—	Device ground	
VM	1	—	Motor supply	Bypass to GND with a 0.1-µF (minimum) ceramic capacitor
VCC	12	—	Device supply	Bypass to GND with a 0.1-µF (minimum) ceramic capacitor
CONTROL				
MODE	11	I	Input mode select	Logic low selects IN/IN mode Logic high selects PH/EN mode Internal pulldown resistor
AIN1/APHASE	10	I	Bridge A input 1/PHASE input	IN/IN mode: Logic high sets AOUT1 high PH/EN mode: Sets direction of H-bridge A Internal pulldown resistor
AIN2/AENBL	9	I	Bridge A input 2/ENABLE input	IN/IN mode: Logic high sets AOUT2 high PH/EN mode: Logic high enables H-bridge A Internal pulldown resistor
BIN1/BPHASE	8	I	Bridge B input 1/PHASE input	IN/IN mode: Logic high sets BOUT1 high PH/EN mode: Sets direction of H-bridge B Internal pulldown resistor
BIN2/BENBL	7	I	Bridge B input 2/ENABLE input	IN/IN mode: Logic high sets BOUT2 high PH/EN mode: Logic high enables H-bridge B Internal pulldown resistor
OUTPUT				
AOUT1	2	O	Bridge A output 1	Connect to motor winding A
AOUT2	3	O	Bridge A output 2	
BOUT1	4	O	Bridge B output 1	Connect to motor winding B
BOUT2	5	O	Bridge B output 2	

(1) Directions: I = input, O = output

6 Specifications

6.1 Absolute Maximum Ratings

See [1][2]

		MIN	MAX	UNIT
	Power supply voltage, VM	–0.3	12	V
	Power supply voltage, VCC	–0.3	7	V
	Digital input pin voltage	–0.5	VCC + 0.5	V
	Peak motor drive output current	Internally limited		A
	Continuous motor drive output current per H-bridge[3]	–1.5	1.5	A
T_J	Operating junction temperature	–40	150	°C
T_{stg}	Storage temperature	–60	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to network ground terminal.
(3) Power dissipation and thermal limits must be observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001[1]	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101[2]	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

T_A = 25°C (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{CC}	Device power supply voltage	2		7	V
V_M	Motor power supply voltage	0		11	V
V_{IN}	Logic level input voltage	0		V_{CC}	V
I_{OUT}	H-bridge output current[1]	0		1.5	A
f_{PWM}	Externally applied PWM frequency	0		250	kHz

(1) Power dissipation and thermal limits must be observed.

6.4 Thermal Information

THERMAL METRIC[1]		DRV8835 DSS (WSON) 12 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	50.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	58	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	19.9	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.9	°C/W
ψ_{JB}	Junction-to-board characterization parameter	20	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	6.9	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics

T_A = 25°C, V_M = 5 V, V_{CC} = 3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY						
I_{VM}	VM operating supply current	No PWM, no load		85	200	µA
		50 kHz PWM, no load		650	2000	
I_{VMQ}	VM sleep mode supply current	V_M = 2 V, V_{CC} = 0 V, all inputs 0 V		5		nA
		V_M = 5 V, V_{CC} = 0 V, all inputs 0 V		10	95	
I_{VCC}	VCC operating supply current			450	2000	µA
V_{UVLO}	VCC undervoltage lockout voltage	V_{CC} rising			2	V
		V_{CC} falling			1.9	
LOGIC-LEVEL INPUTS						
V_{IL}	Input low voltage				0.3 × V_{CC}	V
V_{IH}	Input high voltage		0.5 × V_{CC}			V
I_{IL}	Input low current	V_{IN} = 0	–5		5	µA
I_{IH}	Input high current	V_{IN} = 3.3 V			50	µA
R_{PD}	Pulldown resistance			100		kΩ
H-BRIDGE FETS						
$R_{DS(ON)}$	HS + LS FET on resistance	V_{CC} = 3 V, V_M = 3 V, I_O = 800 mA, T_J = 25°C		370	420	mΩ
		V_{CC} = 5 V, V_M = 5 V, I_O = 800 mA, T_J = 25°C		305	355	
I_{OFF}	OFF-state leakage current				±200	nA
PROTECTION CIRCUITS						
I_{OCP}	Overcurrent protection trip level		1.6		3.5	A
t_{DEG}	Overcurrent de-glitch time			1		µs
t_{OCR}	Overcurrent protection retry time			1		ms
t_{DEAD}	Output dead time			100		ns
t_{TSD}	Thermal shutdown temperature	Die temperature	150	160	180	°C

6.6 Timing Requirements

T_A = 25°C, V_M = 5 V, V_{CC} = 3 V, R_L = 20 Ω

NO.			MIN	MAX	UNIT
1	t_1	Delay time, xPHASE high to xOUT1 low		300	ns
2	t_2	Delay time, xPHASE high to xOUT2 high		200	ns
3	t_3	Delay time, xPHASE low to xOUT1 high		200	ns
4	t_4	Delay time, xPHASE low to xOUT2 low		300	ns
5	t_5	Delay time, xENBL high to xOUTx high		200	ns
6	t_6	Delay time, xENBL high to xOUTx low		300	ns
7	t_7	Output enable time		300	ns
8	t_8	Output disable time		300	ns
9	t_9	Delay time, xINx high to xOUTx high		160	ns
10	t_{10}	Delay time, xINx low to xOUTx low		160	ns
11	t_R	Output rise time	30	188	ns
12	t_F	Output fall time	30	188	ns

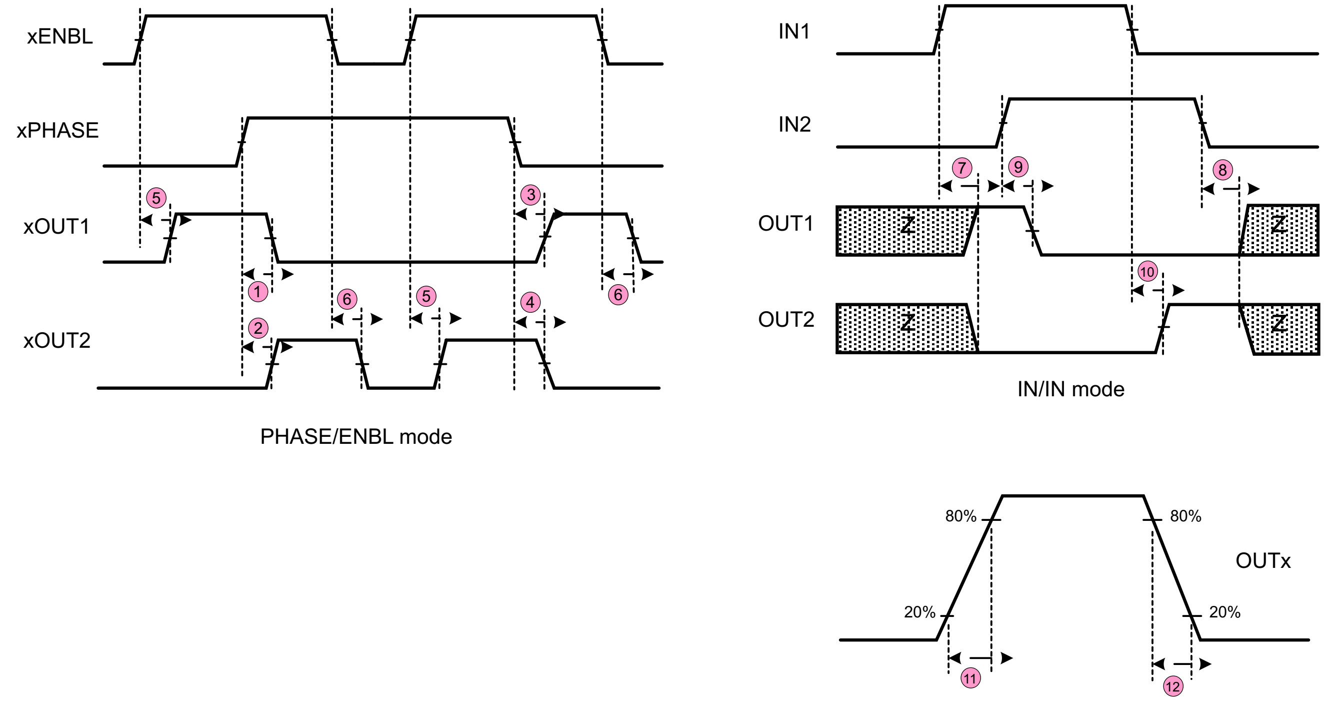


Figure 1. Timing Requirements

6.7 Typical Characteristics

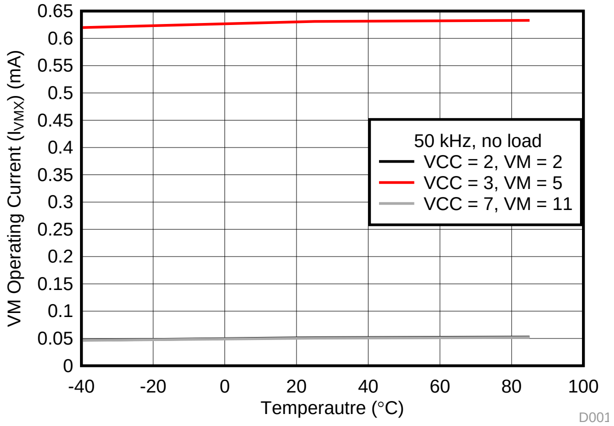


Figure 2. VM Operating Current

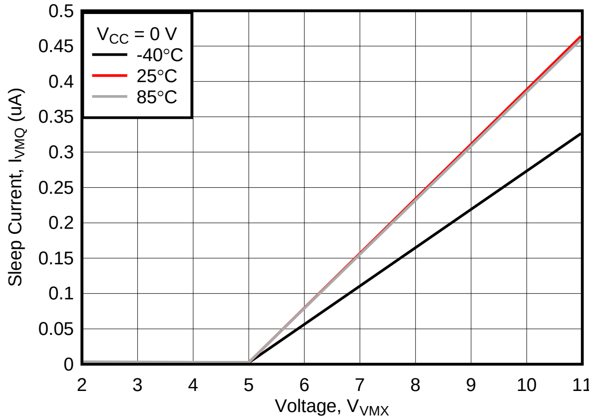


Figure 3. Sleep Current

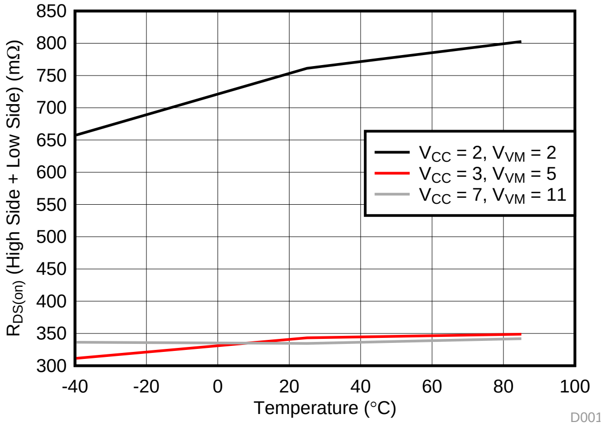


Figure 4. $R_{DS(ON)}$ (High-Side + Low-Side)

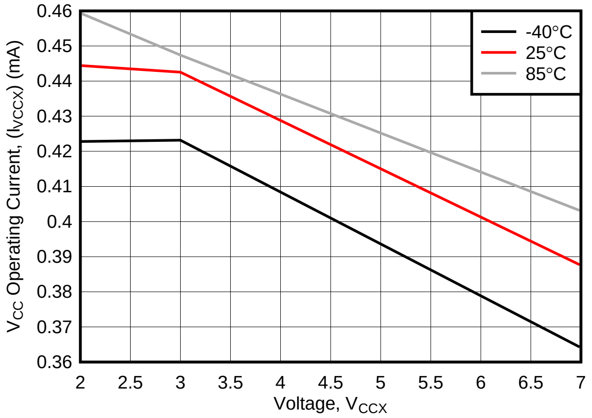


Figure 5. V_{CC} Operating Current

7 Detailed Description

7.1 Overview

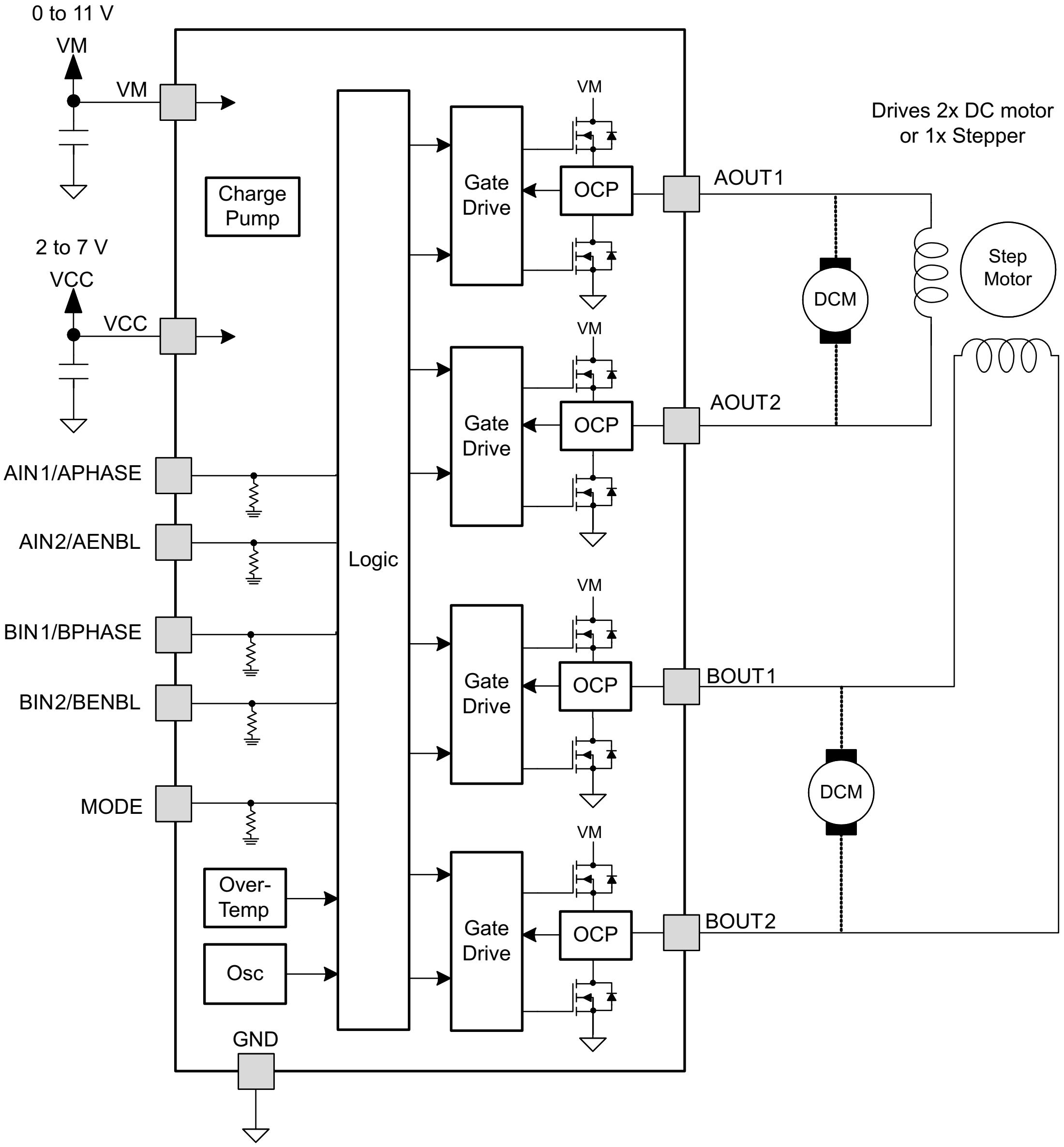
The DRV8835 is an integrated motor-driver solution used for brushed motor control. The device integrates two H-bridges, and drives two DC motor or one stepper motor. The output driver block for each H-bridge consists of N-channel power MOSFETs. An internal charge pump generates the gate drive voltages. Protection features include overcurrent protection, short circuit protection, undervoltage lockout, and overtemperature protection.

The bridges connect in parallel for additional current capability.

The DRV8835 allows separation of the motor voltage and logic voltage if desired. If VM and VCC are less than 7 V, the two voltages can be connected.

The mode pin allow selection of either a PHASE/ENABLE or IN/IN interface.

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Protection Circuits

The DRV8835 is fully protected against undervoltage, overcurrent, and overtemperature events.

7.3.1.1 Overcurrent Protection (OCP)

An analog current limit circuit on each FET limits the current through the FET by removing the gate drive. If this analog current limit persists for longer than the OCP time, all FETs in the H-bridge disable. After approximately 1 ms, the bridge re-enable automatically.

Overcurrent conditions on both high-side and low-side devices; a short to ground, supply, or across the motor winding result in an overcurrent shutdown.

7.3.1.2 Thermal Shutdown (TSD)

If the die temperature exceeds safe limits, all FETs in the H-bridge disable. Operation automatically resumes once the die temperature falls to a safe level.

7.3.1.3 Undervoltage Lockout (UVLO)

If at any time the voltage on the VCC pins falls below the undervoltage lockout threshold voltage, all circuitry in the device disable, and internal logic resets. Operation resumes when VCC rises above the UVLO threshold.

Table 1. Device Protection

FAULT	CONDITION	ERROR REPORT	H-BRIDGE	INTERNAL CIRCUITS	RECOVERY
VCC undervoltage (UVLO)	VCC < VUVLO	None	Disabled	Disabled	VCC > VUVLO
Overcurrent (OCP)	IOUT > IOCP	None	Disabled	Operating	tOCR
Thermal Shutdown (TSD)	TJ > TTSD	None	Disabled	Operating	TJ < TTSD – THYS

7.4 Device Functional Modes

The DRV8835 is active when the VCC is set to a logic high. When in sleep mode, the H-bridge FETs are disabled (HIGH-Z).

Table 2. Device Operating Modes

OPERATING MODE	CONDITION	H-BRIDGE	INTERNAL CIRCUITS
Operating	nSLEEP high	Operating	Operating
Sleep mode	nSLEEP low	Disabled	Disabled
Fault encountered	Any fault condition met	Disabled	See Table 1

7.4.1 Bridge Control

Two control modes are available in the DRV8835: IN/IN mode, and PHASE/ENABLE mode. IN/IN mode is selected if the MODE pin is driven low or left unconnected; PHASE/ENABLE mode is selected if the MODE pin is driven to logic high. Table 3 and Table 4 show the logic for these modes.

Table 3. IN/IN Mode

MODE	xIN1	xIN2	xOUT1	xOUT2	FUNCTION (DC MOTOR)
0	0	0	Z	Z	Coast
0	0	1	L	H	Reverse
0	1	0	H	L	Forward
0	1	1	L	L	Brake

Table 4. Phase/Enable Mode

MODE	xENABLE	xPHASE	xOUT1	xOUT2	FUNCTION (DC MOTOR)
1	0	X	L	L	Brake
1	1	1	L	H	Reverse
1	1	0	H	L	Forward

7.4.2 Sleep Mode

If the VCC pin reaches 0 V, the DRV8835 enters a low-power sleep mode. In this state all unnecessary internal circuitry powers down. For minimum supply current, all inputs should be low (0 V) during sleep mode.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The DRV8835 is used in one or two motor control applications. Configure the DRV8835 in parallel to provide double the current to one motor. The following design procedure can be used to configure the DRV8835 in a brushed motor application.

8.2 Typical Application

The two H-bridges in the DRV8835 connect in parallel for double the current of a single H-bridge. Figure 6 shows the connections.

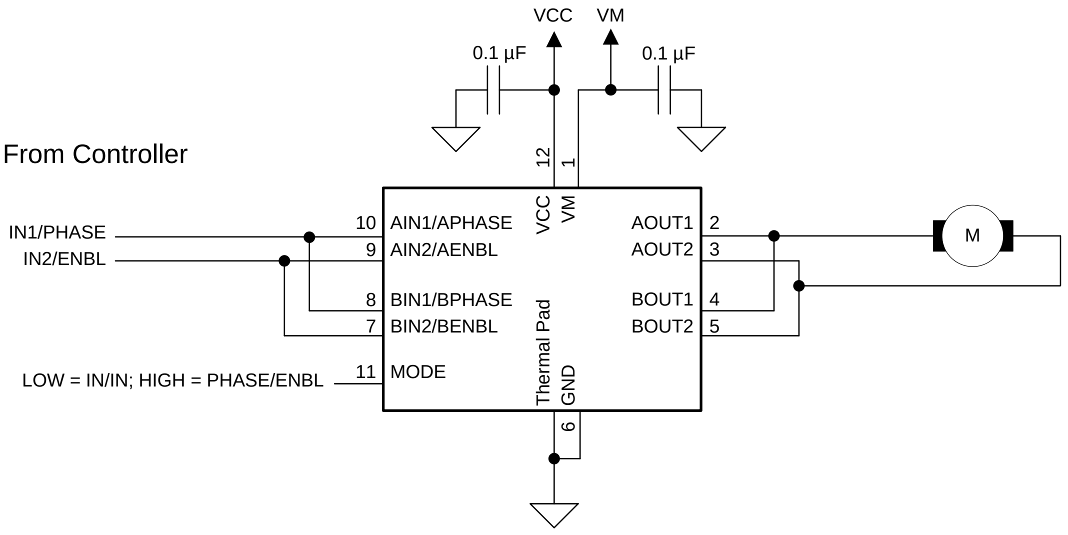


Figure 6. Parallel Mode Connections

8.2.1 Design Requirements

Table 5 lists the design requirements.

Table 5. Design Requirements

DESIGN PARAMETER	REFERENCE	VALUE
Motor voltage	VCC	4 V
Motor RMS current	I_{RMS}	0.3 A
Motor startup current	I_{START}	0.6 A
Motor current trip point	I_{LIMIT}	0.5 A

8.2.2 Detailed Design Procedure

8.2.2.1 Motor Voltage

The appropriate motor voltage depends on the ratings of the motor selected and the desired RPM. A higher voltage spins a brushed DC motor faster with the same PWM duty cycle applied to the power FETs. A higher voltage also increases the rate of current change through the inductive motor windings.

8.2.2.2 Lower-Power Operation

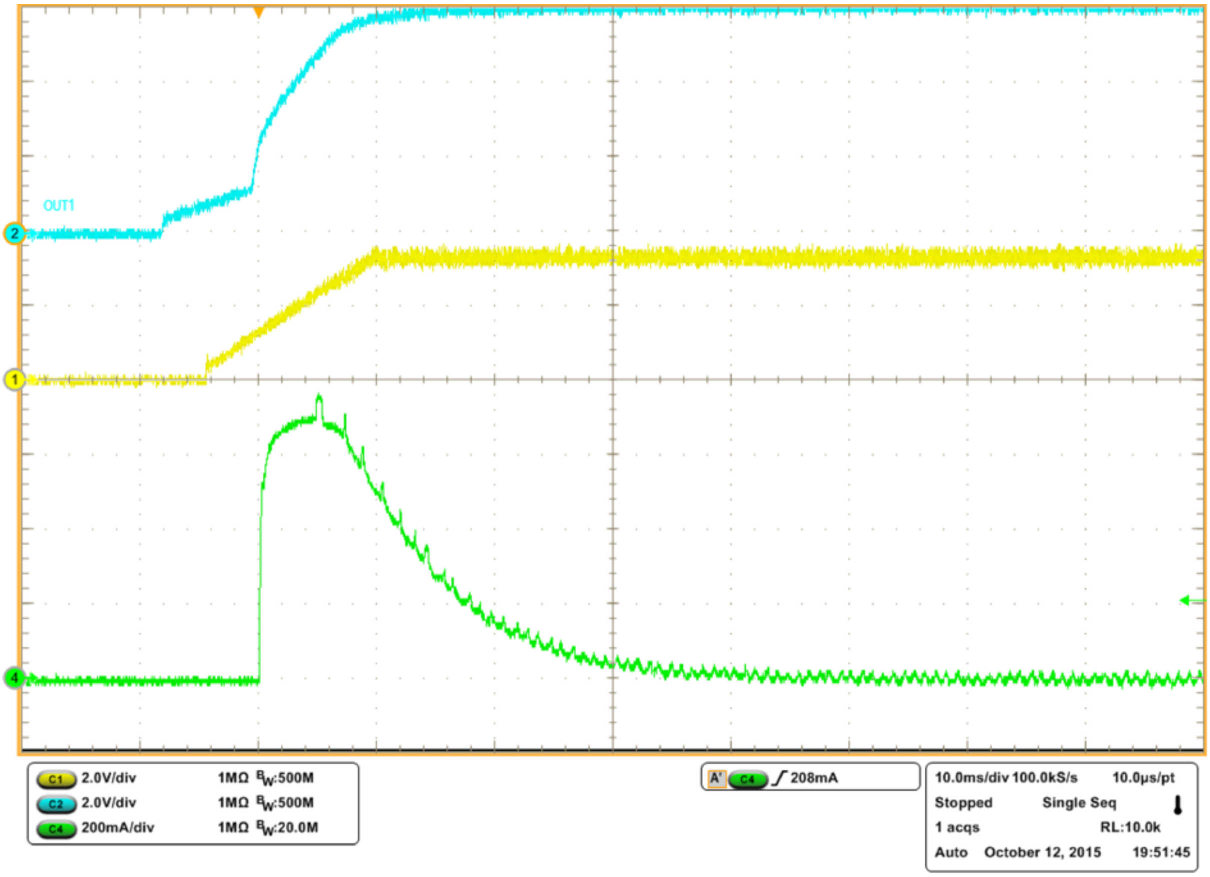
When entering sleep mode, TI recommends setting all inputs as a logic low to minimize system power.

8.2.3 Application Curve

The following scope captures motor startup as V_{CC} ramps from 0 V to 6 V. Channel 1 is VCC, Channel 2 is VM, and Channel 4 is the motor current of an unloaded motor during startup. The motor used is a NMB Technologies Corporation, PPN7PA12C1. As VCC and VM ramp, the current in the motor increases until the motor speed builds up. The motor current then reduces for normal operation.

Inputs are set as follows:

- Mode: IN/IN
- AIN1: High
- AIN2: Low



Channel 1: VM
Channel 2: VCC
Channel 4: Motor current

IN1 = Logic High
IN2 = Logic Low

Motor used: NMB Technologies Corporation, PPN7PA12C1

Figure 7. Motor Startup With No Load

9 Power Supply Recommendations

9.1 Bulk Capacitance

The appropriate local bulk capacitance is an important factor in motor drive system design. More bulk capacitance is generally beneficial, but may increase costs and physical size.

The amount of local capacitance needed depends on a variety of factors, including:

- The highest current required by the motor system
- The power supply's capacitance and ability to source current
- The amount of parasitic inductance between the power supply and motor system
- The acceptable voltage ripple
- The type of motor used (brushed DC, brushless DC, stepper)
- The motor braking method

9.2 Power Supplies and Input Pins

There is a weak pulldown resistor (approximately 100 kΩ) to ground on the input pins.

VCC and VM may be applied and removed in any order. When VCC is removed, the device enters a low power state and draws very little current from VM. To minimize current draw, keep the input pins at 0 V during sleep mode.

The VM voltage supply does not have any undervoltage lockout protection (UVLO), so as long as VCC > 1.8 V, the internal device logic remains active. This means that the VM pin voltage may drop to 0 V, however, the load may not be sufficiently driven at low-VM voltages.

10 Layout

10.1 Layout Guidelines

The VCC pin should be bypassed to GND using low-ESR ceramic bypass capacitors with a recommended value of 0.1 µF rated for VCC. This capacitor should be placed as close to the VCC pin as possible with a thick trace.

The VM pin should be bypassed to GND using low-ESR ceramic bypass capacitors with a recommended value of 0.1 µF rated for VM. This capacitor should be placed as close to the VM pin as possible with a thick trace. The VM pin must bypass to ground using an appropriate bulk capacitor. This component can be an electrolytic and should be located close to the DRV8835.

10.2 Layout Example

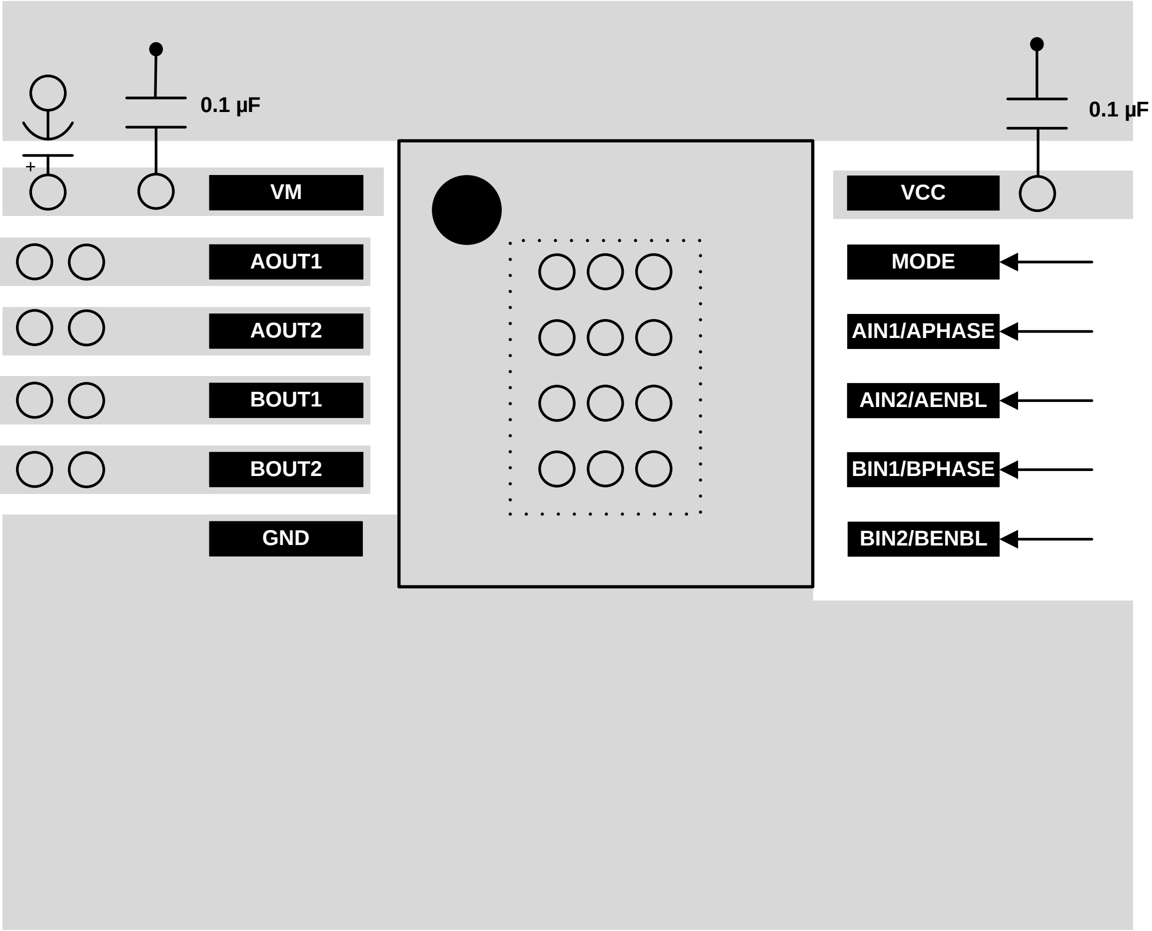


Figure 8. Layout Recommendation

10.3 Thermal Considerations

The DRV8835 has thermal shutdown (TSD) as described above. If the die temperature exceeds approximately 150°C, the device disables until the temperature drops to a safe level.

Any tendency of the device to enter thermal shutdown is an indication of either excessive power dissipation, insufficient heatsinking, or excessively high ambient temperature.

Thermal Considerations (continued)

10.3.1 Power Dissipation

Power dissipation in the DRV8835 is dominated by the power dissipated in the output FET resistance, or $R_{DS(on)}$. Average power dissipation when running both H-bridges can be roughly estimated by Equation 1:

$$P_{TOT} = 2 \times R_{DS(ON)} \times (I_{OUT(RMS)})^2$$

where

- P_{TOT} is the total power dissipation, $R_{DS(ON)}$ is the resistance of the HS plus LS FETs, and $I_{OUT(RMS)}$ is the RMS output current being applied to each winding. $I_{OUT(RMS)}$ is equal to the approximately 0.7× the full-scale output current setting. The factor of 2 comes from the fact that there are two H-bridges. (1)

The maximum amount of power dissipated in the device is dependent on ambient temperature and heatsinking.

NOTE

$R_{DS(on)}$ increases with temperature, so as the device heats, the power dissipation increases. Consider this increase when sizing the heatsink.

The power dissipation of the DRV8835 is a function of RMS motor current and the resistance of each FET ($R_{DS(ON)}$), see Equation 2.

$$\text{Power} \approx I_{RMS}2 \times (\text{High-Side } R_{DS(on)} + \text{Low-Side } R_{DS(on)}) \quad (2)$$

For this example, the ambient temperature is 35°C, and the junction temperature reaches 65°C. At 65°C, the sum of $R_{DS(on)}$ is about 1 Ω. With an example motor current of 0.8 A, the dissipated power in the form of heat will be $0.8\ A^2 \times 1\ \Omega = 0.64\ W$.

The temperature that the DRV8835 reaches depends on the thermal resistance to the air and PCB. It is important to solder the device thermal pad to the PCB ground plane, with vias to the top and bottom board layers, in order dissipate heat into the PCB and reduce the device temperature. In the example used here, the DRV8835 had an effective thermal resistance $R_{\theta JA}$ of 47°C/W, and as shown in Equation 3.

$$T_J = T_A + (P_D \times R_{\theta JA}) = 35°C + (0.64\ W \times 47°C/W) = 65°C \quad (3)$$

10.3.2 Heatsinking

The package uses an exposed pad to remove heat from the device. For proper operation, this pad must thermally connect to copper on the PCB to dissipate heat. On a multi-layer PCB with a ground plane, this can be accomplished by adding a number of vias to connect the thermal pad to the ground plane. On PCBs without internal planes, copper area can be added on either side of the PCB to dissipate heat. If the copper area is on the opposite side of the PCB from the device, thermal vias are used to transfer the heat between top and bottom layers.

For more PCB design details, refer to *QFN/SON PCB Attachment* and *AN-1187 Leadless Leadframe Package (LLP)*, available at www.ti.com.

In general, the more copper area that is provided, the more power can be dissipated.

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation see the following:

- *AN-1187 Leadless Leadframe Package (LLP)* (SNOA401)
- *Calculating Motor Driver Power Dissipation* (SLVA504)
- *DRV8835/DRV8836 Evaluation Module* (SLVU694)
- *QFN/SON PCB Attachment* (SLUA271)
- *Understanding Motor Driver Current Ratings* (SLVA505)

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DRV8835DSSR	Active	Production	WSON (DSS) | 12	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	835

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

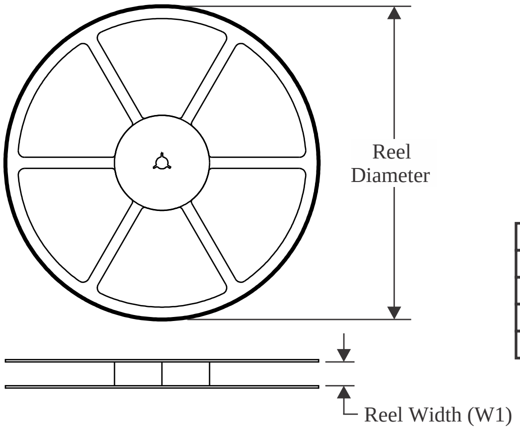
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

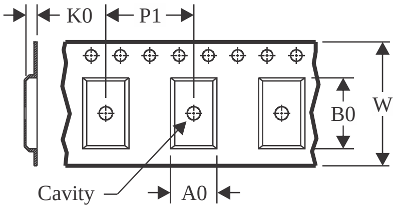
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

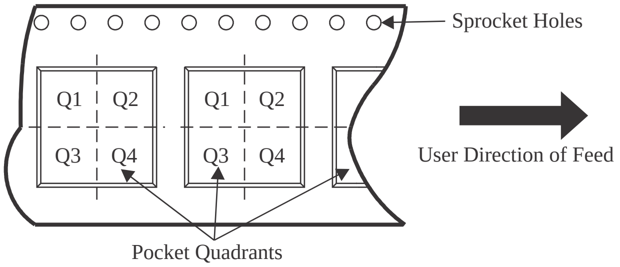


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

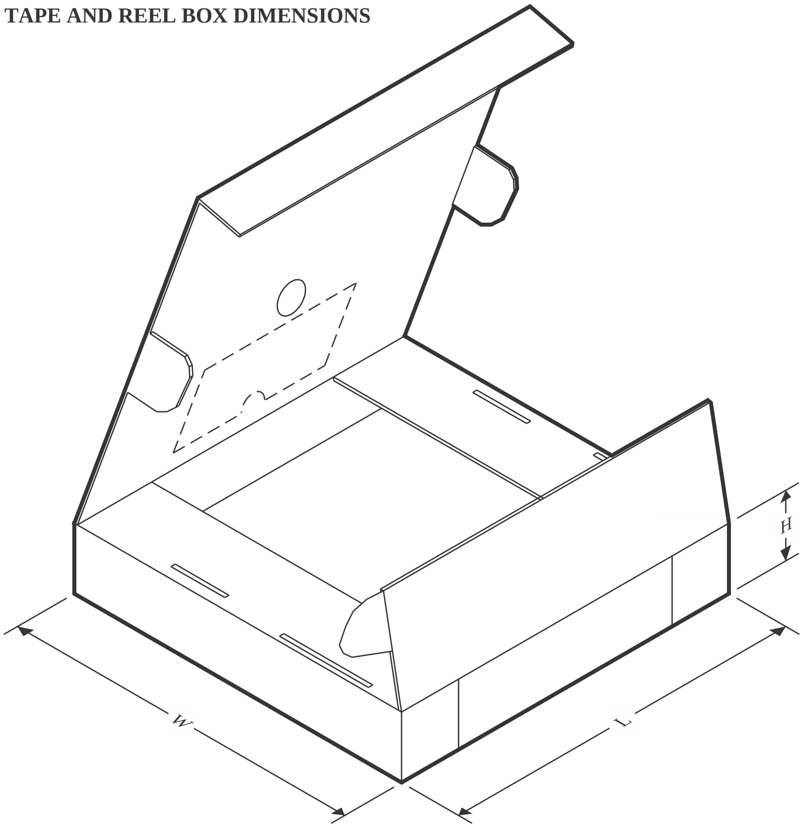
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV8835DSSR	WSON	DSS	12	3000	180.0	8.4	2.25	3.25	1.05	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



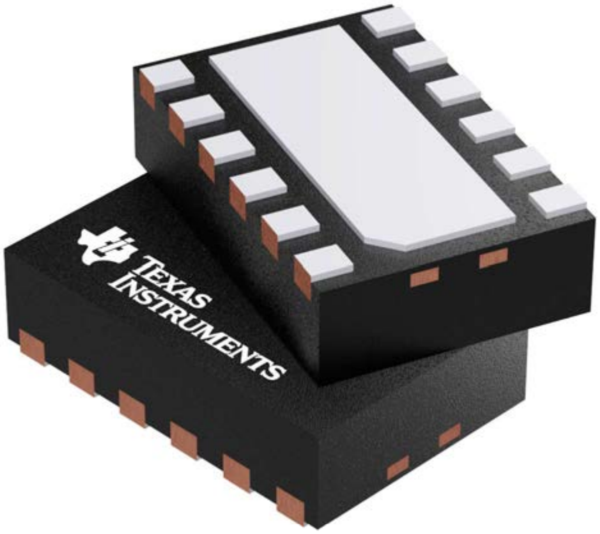
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV8835DSSR	WSON	DSS	12	3000	182.0	182.0	20.0

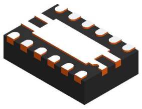
DSS 12

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

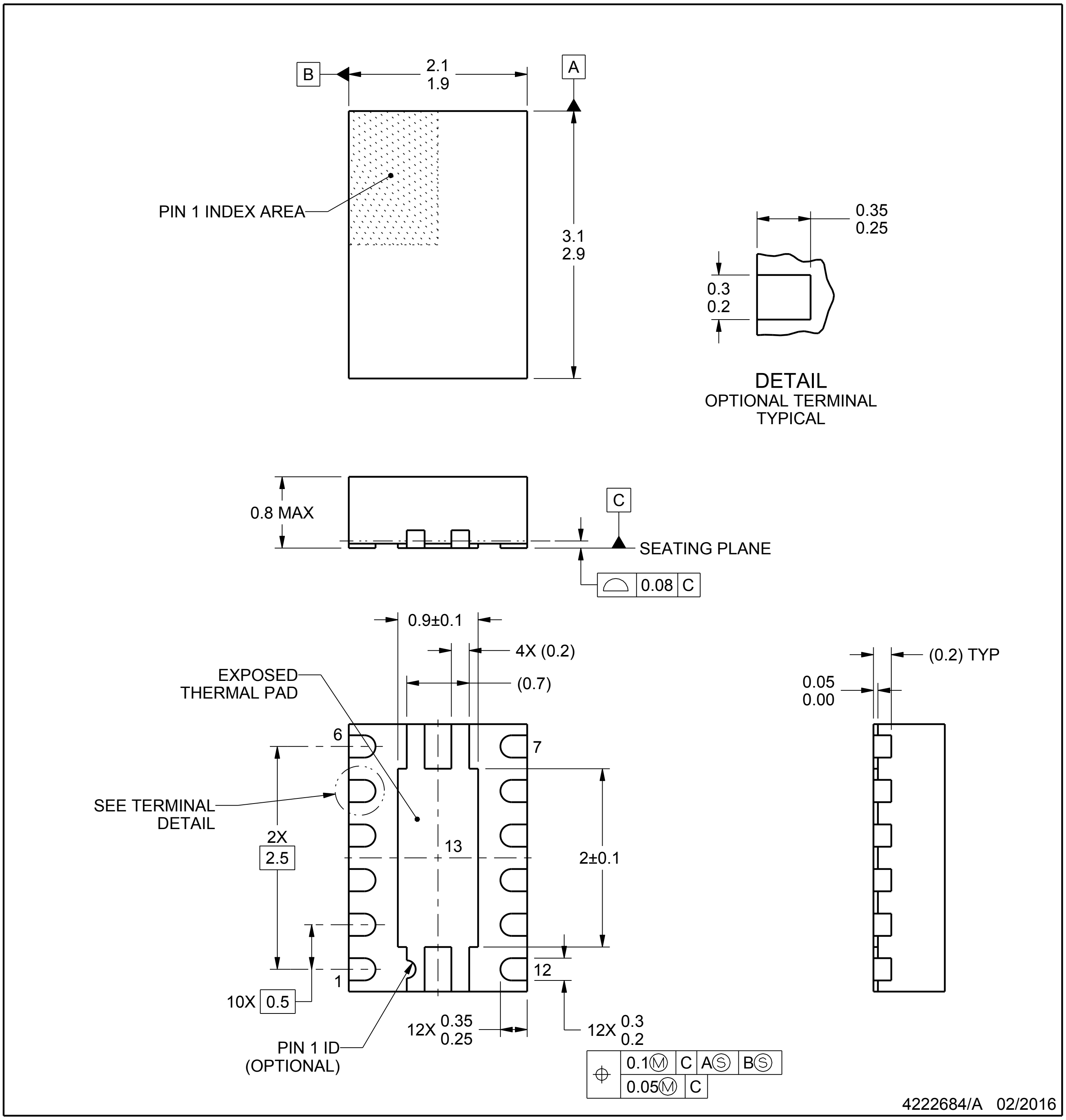


PACKAGE OUTLINE

DSS0012A

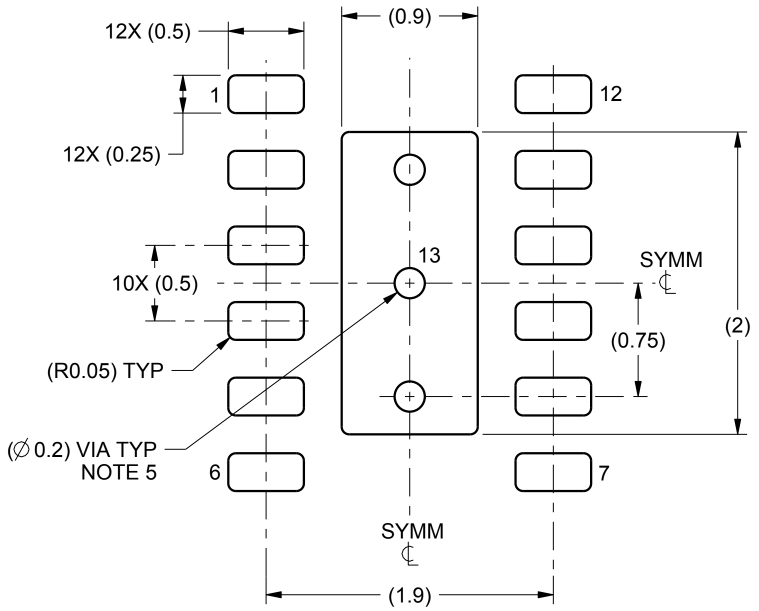
WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

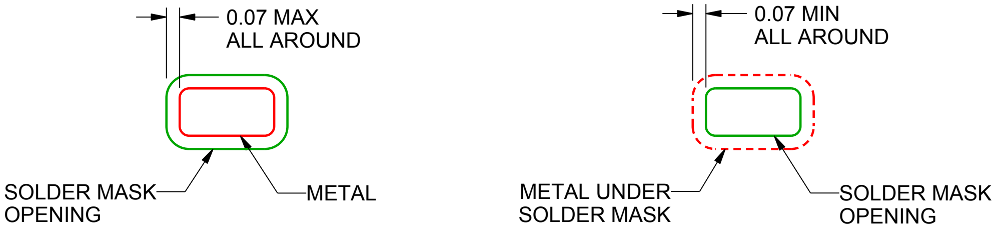


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
SCALE:20X



NON SOLDER MASK
DEFINED
(PREFERRED)

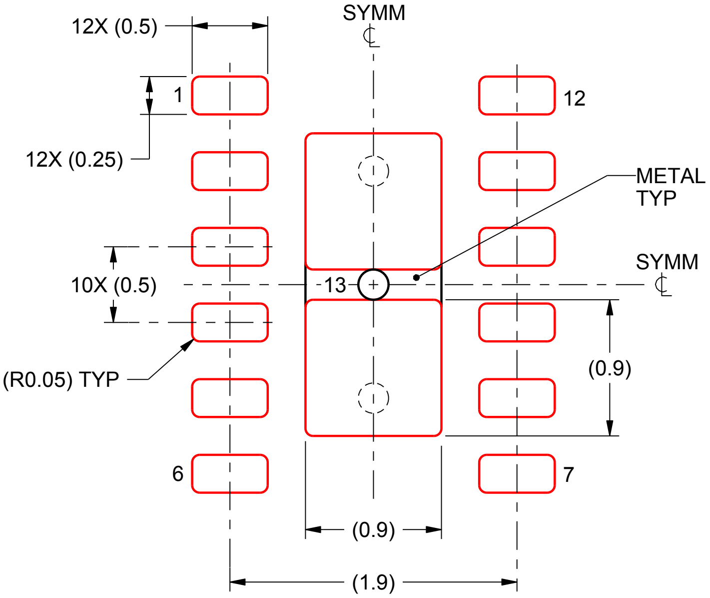
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4222684/A 02/2016

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown. It is recommended that vias located under solder paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 13:
90% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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